



Welcome to E-XFL.COM

What is "[Embedded - Microcontrollers](#)"?

"[Embedded - Microcontrollers](#)" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "[Embedded - Microcontrollers](#)"

Details

Product Status	Obsolete
Core Processor	PIC
Core Size	8-Bit
Speed	4MHz
Connectivity	-
Peripherals	Brown-out Detect/Reset, POR, WDT
Number of I/O	13
Program Memory Size	3.5KB (2K x 14)
Program Memory Type	OTP
EEPROM Size	-
RAM Size	128 x 8
Voltage - Supply (Vcc/Vdd)	2.5V ~ 6V
Data Converters	-
Oscillator Type	External
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	20-SSOP (0.209", 5.30mm Width)
Supplier Device Package	20-SSOP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16lc622t-04i-ss

PIC16C62X

Device Differences

Device	Voltage Range	Oscillator	Process Technology (Microns)
PIC16C620 ⁽³⁾	2.5 - 6.0	See Note 1	0.9
PIC16C621 ⁽³⁾	2.5 - 6.0	See Note 1	0.9
PIC16C622 ⁽³⁾	2.5 - 6.0	See Note 1	0.9
PIC16C620A ⁽⁴⁾	2.7 - 5.5	See Note 1	0.7
PIC16CR620A ⁽²⁾	2.5 - 5.5	See Note 1	0.7
PIC16C621A ⁽⁴⁾	2.7 - 5.5	See Note 1	0.7
PIC16C622A ⁽⁴⁾	2.7 - 5.5	See Note 1	0.7

Note 1: If you change from this device to another device, please verify oscillator characteristics in your application.

2: For ROM parts, operation from 2.5V - 3.0V will require the PIC16LCR62X parts.

3: For OTP parts, operation from 2.5V - 3.0V will require the PIC16LC62X parts.

4: For OTP parts, operations from 2.7V - 3.0V will require the PIC16LC62XA parts.

4.2.2.4 PIE1 Register

This register contains the individual enable bit for the comparator interrupt.

REGISTER 4-4: PIE1 REGISTER (ADDRESS 8CH)

U-0	R/W-0	U-0	U-0	U-0	U-0	U-0	U-0
—	CMIE	—	—	—	—	—	—
bit 7							bit 0

- bit 7 **Unimplemented:** Read as '0'
- bit 6 **CMIE:** Comparator Interrupt Enable bit
1 = Enables the Comparator interrupt
0 = Disables the Comparator interrupt
- bit 5-0 **Unimplemented:** Read as '0'

Legend:

R = Readable bit W = Writable bit U = Unimplemented bit, read as '0'
- n = Value at POR '1' = Bit is set '0' = Bit is cleared x = Bit is unknown

4.2.2.5 PIR1 Register

This register contains the individual flag bit for the comparator interrupt.

Note: Interrupt flag bits get set when an interrupt condition occurs, regardless of the state of its corresponding enable bit or the global enable bit, GIE (INTCON<7>). User software should ensure the appropriate interrupt flag bits are clear prior to enabling an interrupt.

REGISTER 4-5: PIR1 REGISTER (ADDRESS 0CH)

U-0	R/W-0	U-0	U-0	U-0	U-0	U-0	U-0
—	CMIF	—	—	—	—	—	—
bit 7							bit 0

- bit 7 **Unimplemented:** Read as '0'
- bit 6 **CMIF:** Comparator Interrupt Flag bit
1 = Comparator input has changed
0 = Comparator input has not changed
- bit 5-0 **Unimplemented:** Read as '0'

Legend:

R = Readable bit W = Writable bit U = Unimplemented bit, read as '0'
- n = Value at POR '1' = Bit is set '0' = Bit is cleared x = Bit is unknown

5.0 I/O PORTS

The PIC16C62X have two ports, PORTA and PORTB. Some pins for these I/O ports are multiplexed with an alternate function for the peripheral features on the device. In general, when a peripheral is enabled, that pin may not be used as a general purpose I/O pin.

5.1 PORTA and TRISA Registers

PORTA is a 5-bit wide latch. RA4 is a Schmitt Trigger input and an open drain output. Port RA4 is multiplexed with the T0CKI clock input. All other RA port pins have Schmitt Trigger input levels and full CMOS output drivers. All pins have data direction bits (TRIS registers), which can configure these pins as input or output.

A '1' in the TRISA register puts the corresponding output driver in a Hi-impedance mode. A '0' in the TRISA register puts the contents of the output latch on the selected pin(s).

Reading the PORTA register reads the status of the pins, whereas writing to it will write to the port latch. All write operations are read-modify-write operations. So a write to a port implies that the port pins are first read, then this value is modified and written to the port data latch.

The PORTA pins are multiplexed with comparator and voltage reference functions. The operation of these pins are selected by control bits in the CMCON (comparator control register) register and the VRCON (voltage reference control register) register. When selected as a comparator input, these pins will read as '0's.

Note: On RESET, the TRISA register is set to all inputs. The digital inputs are disabled and the comparator inputs are forced to ground to reduce excess current consumption.

TRISA controls the direction of the RA pins, even when they are being used as comparator inputs. The user must make sure to keep the pins configured as inputs when using them as comparator inputs.

The RA2 pin will also function as the output for the voltage reference. When in this mode, the VREF pin is a very high impedance output and must be buffered prior to any external load. The user must configure TRISA<2> bit as an input and use high impedance loads.

In one of the Comparator modes defined by the CMCON register, pins RA3 and RA4 become outputs of the comparators. The TRISA<4:3> bits must be cleared to enable outputs to use this function.

EXAMPLE 5-1: INITIALIZING PORTA

CLRF	PORTA	;Initialize PORTA by setting ;output data latches
MOVLW	0x07	;Turn comparators off and
MOVWF	CMCON	;enable pins for I/O ;functions
BSF	STATUS, RP0	;Select Bank1
MOVLW	0x1F	;Value used to initialize ;data direction
MOVWF	TRISA	;Set RA<4:0> as inputs ;TRISA<7:5> are always ;read as '0'.

FIGURE 5-1: BLOCK DIAGRAM OF RA1:RA0 PINS

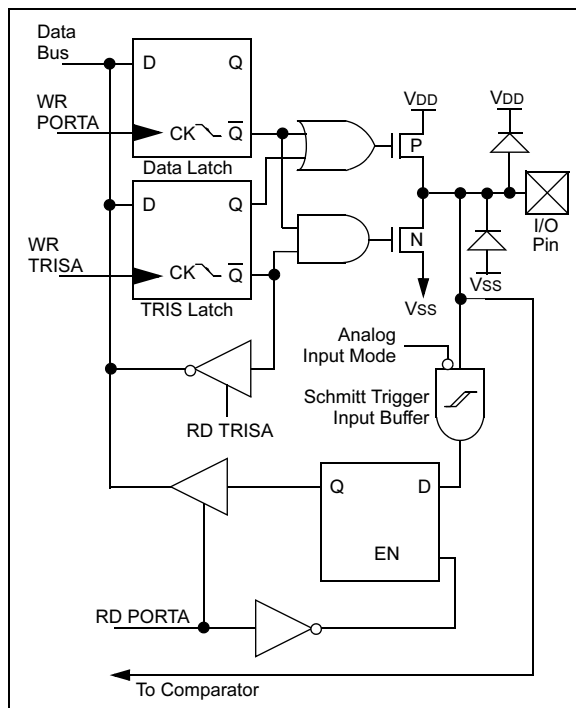
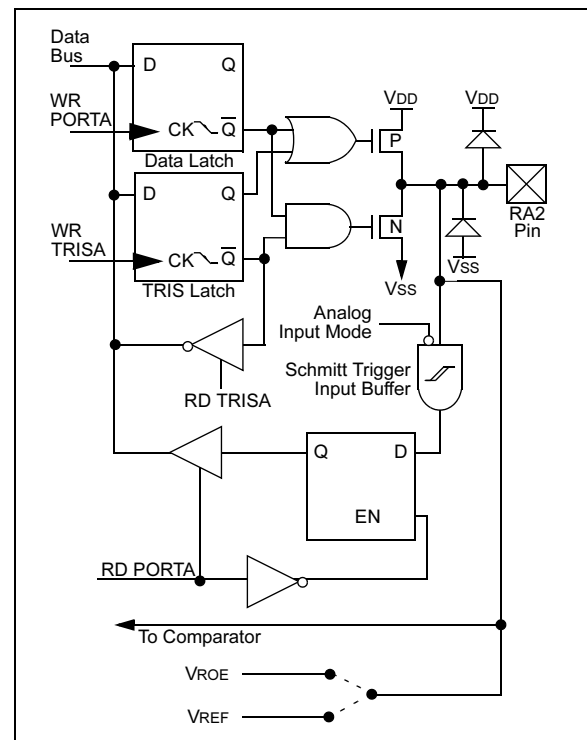


FIGURE 5-2: BLOCK DIAGRAM OF RA2 PIN



--

--



6.0 TIMER0 MODULE

The Timer0 module timer/counter has the following features:

- 8-bit timer/counter
- Readable and writable
- 8-bit software programmable prescaler
- Internal or external clock select
- Interrupt on overflow from FFh to 00h
- Edge select for external clock

Figure 6-1 is a simplified block diagram of the Timer0 module.

Timer mode is selected by clearing the T0CS bit (OPTION<5>). In Timer mode, the TMR0 will increment every instruction cycle (without prescaler). If Timer0 is written, the increment is inhibited for the following two cycles (Figure 6-2 and Figure 6-3). The user can work around this by writing an adjusted value to TMR0.

Counter mode is selected by setting the T0CS bit. In this mode, Timer0 will increment either on every rising or falling edge of pin RA4/T0CKI. The incrementing edge is determined by the source edge (T0SE) control bit (OPTION<4>). Clearing the T0SE bit selects the rising edge. Restrictions on the external clock input are discussed in detail in Section 6.2.

The prescaler is shared between the Timer0 module and the Watchdog Timer. The prescaler assignment is controlled in software by the control bit PSA (OPTION<3>). Clearing the PSA bit will assign the prescaler to Timer0. The prescaler is not readable or writable. When the prescaler is assigned to the Timer0 module, prescale value of 1:2, 1:4, ..., 1:256 are selectable. Section 6.3 details the operation of the prescaler.

6.1 TIMER0 Interrupt

Timer0 interrupt is generated when the TMR0 register timer/counter overflows from FFh to 00h. This overflow sets the T0IF bit. The interrupt can be masked by clearing the T0IE bit (INTCON<5>). The T0IF bit (INTCON<2>) must be cleared in software by the Timer0 module interrupt service routine before re-enabling this interrupt. The Timer0 interrupt cannot wake the processor from SLEEP, since the timer is shut off during SLEEP. See Figure 6-4 for Timer0 interrupt timing.

FIGURE 6-1: TIMER0 BLOCK DIAGRAM

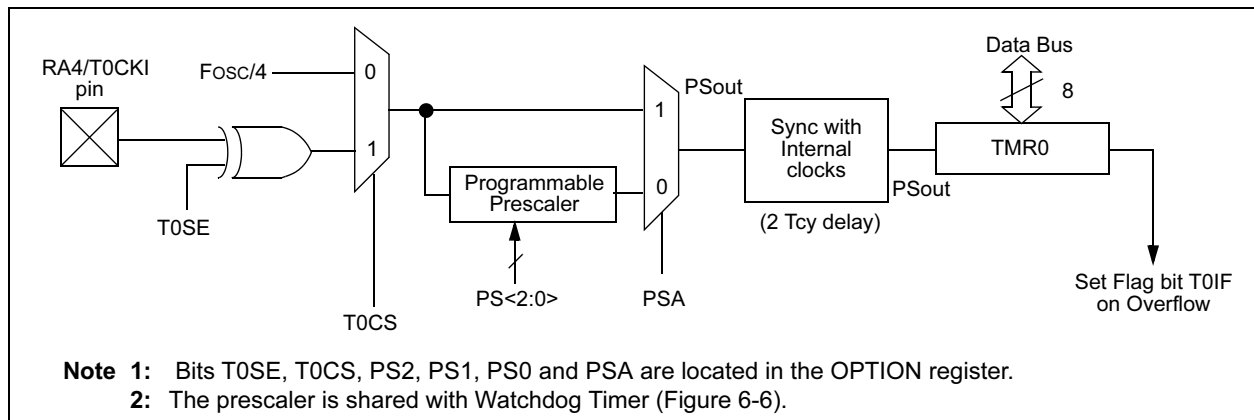
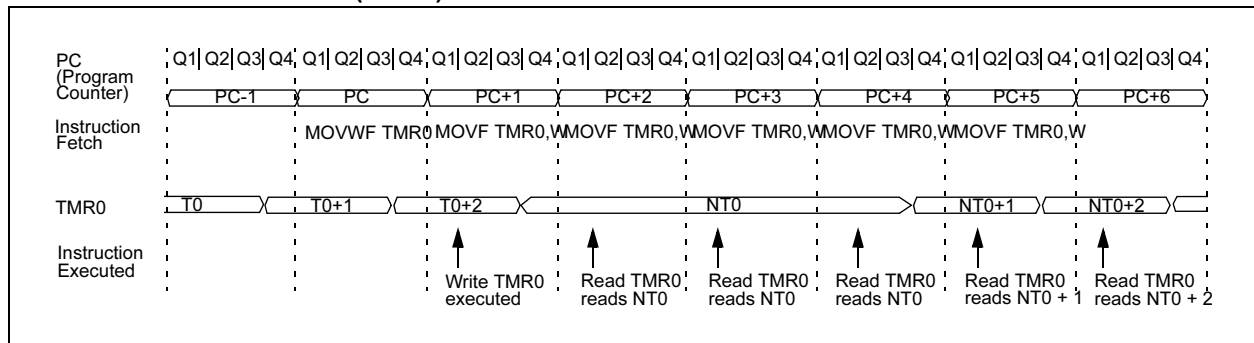


FIGURE 6-2: TIMER0 (TMR0) TIMING: INTERNAL CLOCK/NO PRESCALER



9.2 Oscillator Configurations

9.2.1 OSCILLATOR TYPES

The PIC16C62X devices can be operated in four different oscillator options. The user can program two configuration bits (FOSC1 and FOSC0) to select one of these four modes:

- LP Low Power Crystal
- XT Crystal/Resonator
- HS High Speed Crystal/Resonator
- RC Resistor/Capacitor

9.2.2 CRYSTAL OSCILLATOR / CERAMIC RESONATORS

In XT, LP or HS modes, a crystal or ceramic resonator is connected to the OSC1 and OSC2 pins to establish oscillation (Figure 9-1). The PIC16C62X oscillator design requires the use of a parallel cut crystal. Use of a series cut crystal may give a frequency out of the crystal manufacturers specifications. When in XT, LP or HS modes, the device can have an external clock source to drive the OSC1 pin (Figure 9-2).

FIGURE 9-1: CRYSTAL OPERATION (OR CERAMIC RESONATOR) (HS, XT OR LP OSC CONFIGURATION)

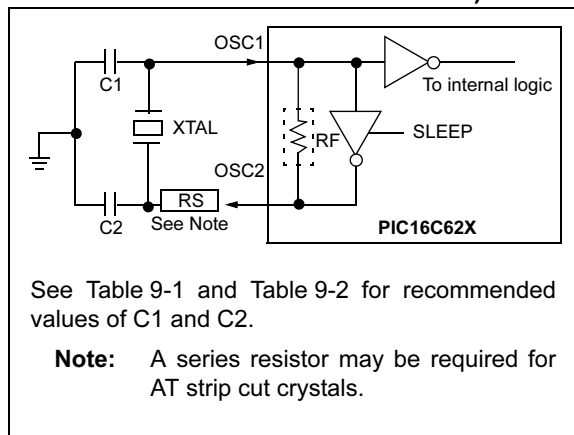


FIGURE 9-2: EXTERNAL CLOCK INPUT OPERATION (HS, XT OR LP OSC CONFIGURATION)

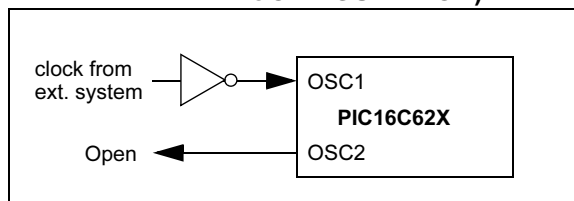


TABLE 9-1: CAPACITOR SELECTION FOR CERAMIC RESONATORS

Ranges Characterized:			
Mode	Freq	OSC1(C1)	OSC2(C2)
XT	455 kHz	22 - 100 pF	22 - 100 pF
	2.0 MHz	15 - 68 pF	15 - 68 pF
	4.0 MHz	15 - 68 pF	15 - 68 pF
HS	8.0 MHz	10 - 68 pF	10 - 68 pF
	16.0 MHz	10 - 22 pF	10 - 22 pF

Higher capacitance increases the stability of the oscillator but also increases the start-up time. These values are for design guidance only. Since each resonator has its own characteristics, the user should consult the resonator manufacturer for appropriate values of external components.

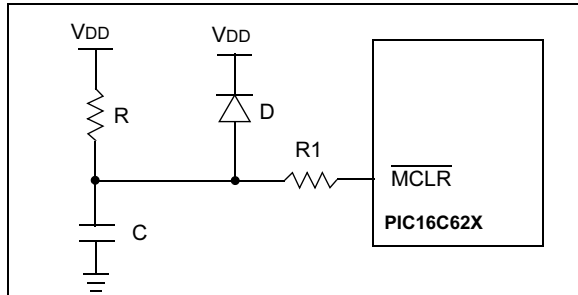
TABLE 9-2: CAPACITOR SELECTION FOR CRYSTAL OSCILLATOR

Mode	Freq	OSC1(C1)	OSC2(C2)
LP	32 kHz	68 - 100 pF	68 - 100 pF
	200 kHz	15 - 30 pF	15 - 30 pF
XT	100 kHz	68 - 150 pF	150 - 200 pF
	2 MHz	15 - 30 pF	15 - 30 pF
	4 MHz	15 - 30 pF	15 - 30 pF
HS	8 MHz	15 - 30 pF	15 - 30 pF
	10 MHz	15 - 30 pF	15 - 30 pF
	20 MHz	15 - 30 pF	15 - 30 pF

Higher capacitance increases the stability of the oscillator but also increases the start-up time. These values are for design guidance only. Rs may be required in HS mode as well as XT mode to avoid overdriving crystals with low drive level specification. Since each crystal has its own characteristics, the user should consult the crystal manufacturer for appropriate values of external components.

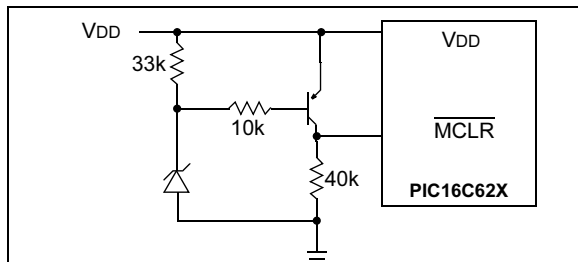
PIC16C62X

FIGURE 9-11: EXTERNAL POWER-ON RESET CIRCUIT (FOR SLOW VDD POWER-UP)



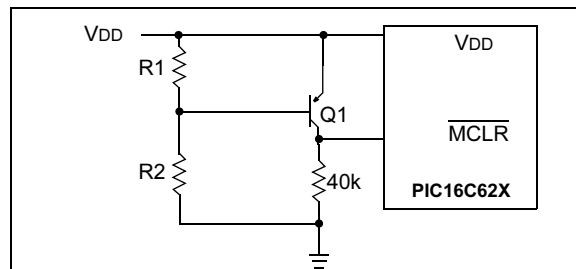
- Note 1:** External Power-on Reset circuit is required only if VDD power-up slope is too slow. The diode D helps discharge the capacitor quickly when VDD powers down.
- 2:** < 40 kΩ is recommended to make sure that voltage drop across R does not violate the device's electrical specification.
- 3:** R1 = 100Ω to 1 kΩ will limit any current flowing into MCLR from external capacitor C in the event of MCLR/VPP pin breakdown due to Electrostatic Discharge (ESD) or Electrical Overstress (EOS).

FIGURE 9-12: EXTERNAL BROWN-OUT PROTECTION CIRCUIT 1



- Note 1:** This circuit will activate RESET when VDD goes below (Vz + 0.7V) where Vz = Zener voltage.
- 2:** Internal Brown-out Reset circuitry should be disabled when using this circuit.

FIGURE 9-13: EXTERNAL BROWN-OUT PROTECTION CIRCUIT 2

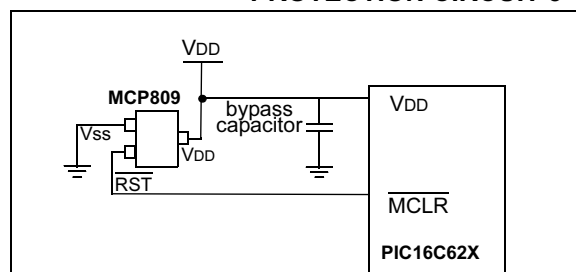


- Note 1:** This brown-out circuit is less expensive, albeit less accurate. Transistor Q1 turns off when VDD is below a certain level such that:

$$V_{DD} \times \frac{R1}{R1 + R2} = 0.7V$$

- 2:** Internal Brown-out Reset should be disabled when using this circuit.
- 3:** Resistors should be adjusted for the characteristics of the transistor.

FIGURE 9-14: EXTERNAL BROWN-OUT PROTECTION CIRCUIT 3



This brown-out protection circuit employs Microchip Technology's MCP809 microcontroller supervisor. The MCP8XX and MCP1XX families of supervisors provide push-pull and open collector outputs with both high and low active RESET pins. There are 7 different trip point selections to accommodate 5V and 3V systems.

9.5 Interrupts

The PIC16C62X has 4 sources of interrupt:

- External interrupt RB0/INT
- TMR0 overflow interrupt
- PORTB change interrupts (pins RB<7:4>)
- Comparator interrupt

The interrupt control register (INTCON) records individual interrupt requests in flag bits. It also has individual and global interrupt enable bits.

A global interrupt enable bit, GIE (INTCON<7>) enables (if set) all un-masked interrupts or disables (if cleared) all interrupts. Individual interrupts can be disabled through their corresponding enable bits in INTCON register. GIE is cleared on RESET.

The “return from interrupt” instruction, RETFIE, exits interrupt routine, as well as sets the GIE bit, which re-enable RB0/INT interrupts.

The INT pin interrupt, the RB port change interrupt and the TMR0 overflow interrupt flags are contained in the INTCON register.

The peripheral interrupt flag is contained in the special register PIR1. The corresponding interrupt enable bit is contained in special registers PIE1.

When an interrupt is responded to, the GIE is cleared to disable any further interrupt, the return address is pushed into the stack and the PC is loaded with 0004h.

Once in the interrupt service routine, the source(s) of the interrupt can be determined by polling the interrupt flag bits. The interrupt flag bit(s) must be cleared in software before re-enabling interrupts to avoid RB0/INT recursive interrupts.

For external interrupt events, such as the INT pin or PORTB change interrupt, the interrupt latency will be three or four instruction cycles. The exact latency depends when the interrupt event occurs (Figure 9-16). The latency is the same for one or two cycle instructions. Once in the interrupt service routine, the source(s) of the interrupt can be determined by polling the interrupt flag bits. The interrupt flag bit(s) must be cleared in software before re-enabling interrupts to avoid multiple interrupt requests.

Note 1: Individual interrupt flag bits are set regardless of the status of their corresponding mask bit or the GIE bit.

2: When an instruction that clears the GIE bit is executed, any interrupts that were pending for execution in the next cycle are ignored. The CPU will execute a NOP in the cycle immediately following the instruction which clears the GIE bit. The interrupts which were ignored are still pending to be serviced when the GIE bit is set again.

FIGURE 9-15: INTERRUPT LOGIC

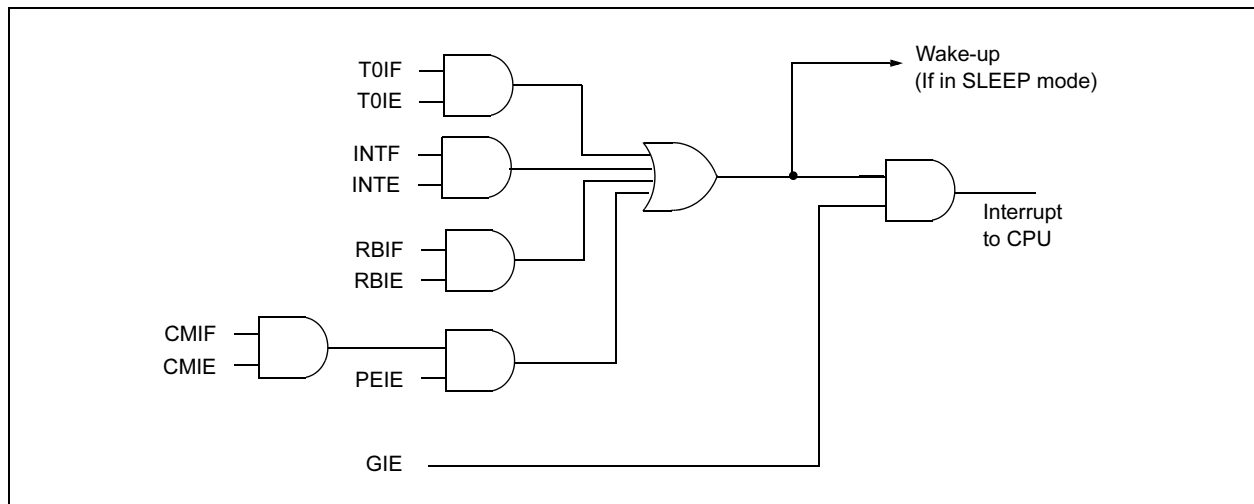


TABLE 9-6: SUMMARY OF INTERRUPT REGISTERS

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR Reset	Value on all other RESETS ⁽¹⁾
0Bh	INTCON	GIE	PEIE	TOIE	INTE	RBIE	TOIF	INTF	RBIF	0000 000x	0000 000u
0Ch	PIR1	—	CMIF	—	—	—	—	—	—	-0-- ----	-0-- ----
8Ch	PIE1	—	CMIE	—	—	—	—	—	—	-0-- ----	-0-- ----

Note 1: Other (non Power-up) Resets include MCLR Reset, Brown-out Reset and Watchdog Timer Reset during normal operation.

9.6 Context Saving During Interrupts

During an interrupt, only the return PC value is saved on the stack. Typically, users may wish to save key registers during an interrupt (e.g., W register and STATUS register). This will have to be implemented in software.

Example 9-3 stores and restores the STATUS and W registers. The user register, W_TEMP, must be defined in both banks and must be defined at the same offset from the bank base address (i.e., W_TEMP is defined at 0x20 in Bank 0 and it must also be defined at 0xA0 in Bank 1). The user register, STATUS_TEMP, must be defined in Bank 0. The Example 9-3:

- Stores the W register
- Stores the STATUS register in Bank 0
- Executes the ISR code
- Restores the STATUS (and bank select bit register)
- Restores the W register

EXAMPLE 9-3: SAVING THE STATUS AND W REGISTERS IN RAM

```

MOVWF  W_TEMP      ;copy W to temp register,
                    ;could be in either bank
SWAPF  STATUS,W     ;swap status to be saved
                    ;into W
BCF    STATUS,RP0    ;change to bank 0 regardless
                    ;of current bank
MOVWF  STATUS_TEMP  ;save status to bank 0
                    ;register
:
:    (ISR)
:
SWAPF  STATUS_TEMP, ;swap STATUS_TEMP register
W      ;into W, sets bank to origi-
        ;nal
        ;state
MOVWF  STATUS       ;move W into STATUS register
SWAPF  W_TEMP,F     ;swap W_TEMP
SWAPF  W_TEMP,W     ;swap W_TEMP into W

```

10.0 INSTRUCTION SET SUMMARY

Each PIC16C62X instruction is a 14-bit word divided into an OPCODE which specifies the instruction type and one or more operands which further specify the operation of the instruction. The PIC16C62X instruction set summary in Table 10-2 lists **byte-oriented**, **bit-oriented**, and **literal and control** operations. Table 10-1 shows the opcode field descriptions.

For **byte-oriented** instructions, 'f' represents a file register designator and 'd' represents a destination designator. The file register designator specifies which file register is to be used by the instruction.

The destination designator specifies where the result of the operation is to be placed. If 'd' is zero, the result is placed in the W register. If 'd' is one, the result is placed in the file register specified in the instruction.

For **bit-oriented** instructions, 'b' represents a bit field designator which selects the number of the bit affected by the operation, while 'f' represents the number of the file in which the bit is located.

For **literal and control** operations, 'k' represents an eight or eleven bit constant or literal value.

TABLE 10-1: OPCODE FIELD DESCRIPTIONS

Field	Description
f	Register file address (0x00 to 0x7F)
W	Working register (accumulator)
b	Bit address within an 8-bit file register
k	Literal field, constant data or label
x	Don't care location (= 0 or 1) The assembler will generate code with x = 0. It is the recommended form of use for compatibility with all Microchip software tools.
d	Destination select; d = 0: store result in W, d = 1: store result in file register f. Default is d = 1
label	Label name
TOS	Top of Stack
PC	Program Counter
PCLATH	Program Counter High Latch
GIE	Global Interrupt Enable bit
WDT	Watchdog Timer/Counter
TO	Time-out bit
PD	Power-down bit
dest	Destination either the W register or the specified register file location
[]	Options
()	Contents
→	Assigned to
< >	Register bit field
∈	In the set of
italics	User defined term (font is courier)

The instruction set is highly orthogonal and is grouped into three basic categories:

- **Byte-oriented** operations
- **Bit-oriented** operations
- **Literal and control** operations

All instructions are executed within one single instruction cycle, unless a conditional test is true or the program counter is changed as a result of an instruction. In this case, the execution takes two instruction cycles with the second cycle executed as a NOP. One instruction cycle consists of four oscillator periods. Thus, for an oscillator frequency of 4 MHz, the normal instruction execution time is 1 μs. If a conditional test is true or the program counter is changed as a result of an instruction, the instruction execution time is 2 μs.

Table 10-1 lists the instructions recognized by the MPASM™ assembler.

Figure 10-1 shows the three general formats that the instructions can have.

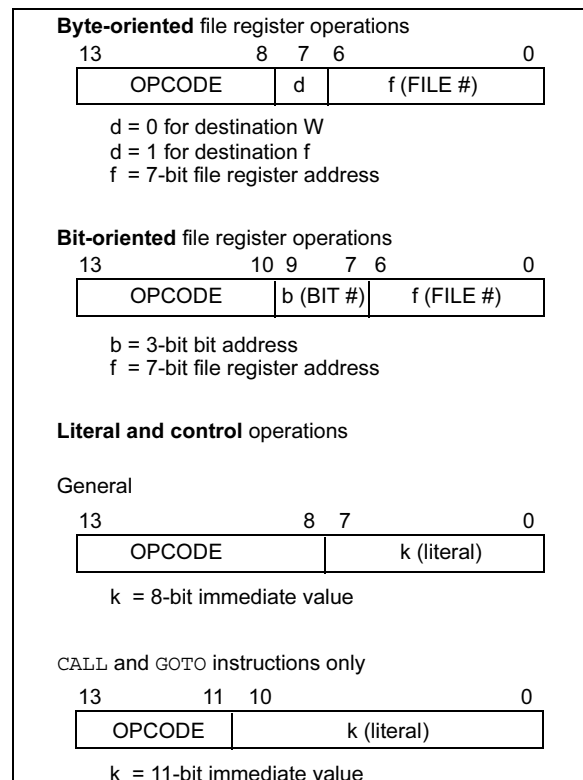
Note: To maintain upward compatibility with future PICmicro® products, do not use the OPTION and TRIS instructions.

All examples use the following format to represent a hexadecimal number:

0xhh

where h signifies a hexadecimal digit.

FIGURE 10-1: GENERAL FORMAT FOR INSTRUCTIONS



MOVF		Move f			
Syntax:	[<i>label</i>] MOVF f,d				
Operands:	$0 \leq f \leq 127$ $d \in [0,1]$				
Operation:	(f) $\rightarrow$ (dest)				
Status Affected:	Z				
Encoding:	00	1000	dfff	ffff	
Description:	The contents of register f is moved to a destination dependent upon the status of d. If d = 0, destination is W register. If d = 1, the destination is file register f itself. d = 1 is useful to test a file register since status flag Z is affected.				
Words:	1				
Cycles:	1				
Example	MOVF FSR, 0				
	After Instruction				
	W	=	value in FSR		
	register				
	Z	=	1		

MOVWF	Move W to f				
Syntax:	[<i>label</i>] MOVWF f				
Operands:	0 ≤ f ≤ 127				
Operation:	(W) → (f)				
Status Affected:	None				
Encoding:	<table><tr><td>00</td><td>0000</td><td>1fff</td><td>ffff</td></tr></table>	00	0000	1fff	ffff
00	0000	1fff	ffff		
Description:	Move data from W register to register 'f'.				
Words:	1				
Cycles:	1				
Example	MOVWF OPTION Before Instruction OPTION = 0xFF W = 0x4F After Instruction OPTION = 0x4F W = 0x4F				

NOP	No Operation			
Syntax:	[<i>label</i>] NOP			
Operands:	None			
Operation:	No operation			
Status Affected:	None			
Encoding:	00	0000	0xx0	0000
Description:	No operation.			
Words:	1			
Cycles:	1			
Example	NOP			

OPTION	Load Option Register				
Syntax:	[<i>label</i>] OPTION				
Operands:	None				
Operation:	(W) → OPTION				
Status Affected:	None				
Encoding:	<table><tr><td>00</td><td>0000</td><td>0110</td><td>0010</td></tr></table>	00	0000	0110	0010
00	0000	0110	0010		
Description:	The contents of the W register are loaded in the OPTION register. This instruction is supported for code compatibility with PIC16C5X products. Since OPTION is a readable/writable register, the user can directly address it.				
Words:	1				
Cycles:	1				
Example	To maintain upward compatibility with future PICmicro[®] products, do not use this instruction.				

11.14 PICDEM 1 PICmicro Demonstration Board

The PICDEM 1 demonstration board demonstrates the capabilities of the PIC16C5X (PIC16C54 to PIC16C58A), PIC16C61, PIC16C62X, PIC16C71, PIC16C8X, PIC17C42, PIC17C43 and PIC17C44. All necessary hardware and software is included to run basic demo programs. The sample microcontrollers provided with the PICDEM 1 demonstration board can be programmed with a PRO MATE II device programmer, or a PICSTART Plus development programmer. The PICDEM 1 demonstration board can be connected to the MPLAB ICE in-circuit emulator for testing. A prototype area extends the circuitry for additional application components. Features include an RS-232 interface, a potentiometer for simulated analog input, push button switches and eight LEDs.

11.15 PICDEM.net Internet/Ethernet Demonstration Board

The PICDEM.net demonstration board is an Internet/Ethernet demonstration board using the PIC18F452 microcontroller and TCP/IP firmware. The board supports any 40-pin DIP device that conforms to the standard pinout used by the PIC16F877 or PIC18C452. This kit features a user friendly TCP/IP stack, web server with HTML, a 24L256 Serial EEPROM for Xmodem download to web pages into Serial EEPROM, ICSP/MPLAB ICD 2 interface connector, an Ethernet interface, RS-232 interface, and a 16 x 2 LCD display. Also included is the book and CD-ROM *"TCP/IP Lean, Web Servers for Embedded Systems,"* by Jeremy Bentham

11.16 PICDEM 2 Plus Demonstration Board

The PICDEM 2 Plus demonstration board supports many 18-, 28-, and 40-pin microcontrollers, including PIC16F87X and PIC18FXX2 devices. All the necessary hardware and software is included to run the demonstration programs. The sample microcontrollers provided with the PICDEM 2 demonstration board can be programmed with a PRO MATE II device programmer, PICSTART Plus development programmer, or MPLAB ICD 2 with a Universal Programmer Adapter. The MPLAB ICD 2 and MPLAB ICE in-circuit emulators may also be used with the PICDEM 2 demonstration board to test firmware. A prototype area extends the circuitry for additional application components. Some of the features include an RS-232 interface, a 2 x 16 LCD display, a piezo speaker, an on-board temperature sensor, four LEDs, and sample PIC18F452 and PIC16F877 FLASH microcontrollers.

11.17 PICDEM 3 PIC16C92X Demonstration Board

The PICDEM 3 demonstration board supports the PIC16C923 and PIC16C924 in the PLCC package. All the necessary hardware and software is included to run the demonstration programs.

11.18 PICDEM 4 8/14/18-Pin Demonstration Board

The PICDEM 4 can be used to demonstrate the capabilities of the 8-, 14-, and 18-pin PIC16XXXX and PIC18XXXX MCUs, including the PIC16F818/819, PIC16F87/88, PIC16F62XA and the PIC18F1320 family of microcontrollers. PICDEM 4 is intended to showcase the many features of these low pin count parts, including LIN and Motor Control using ECCP. Special provisions are made for low power operation with the supercapacitor circuit, and jumpers allow on-board hardware to be disabled to eliminate current draw in this mode. Included on the demo board are provisions for Crystal, RC or Canned Oscillator modes, a five volt regulator for use with a nine volt wall adapter or battery, DB-9 RS-232 interface, ICD connector for programming via ICSP and development with MPLAB ICD 2, 2x16 liquid crystal display, PCB footprints for H-Bridge motor driver, LIN transceiver and EEPROM. Also included are: header for expansion, eight LEDs, four potentiometers, three push buttons and a prototyping area. Included with the kit is a PIC16F627A and a PIC18F1320. Tutorial firmware is included along with the User's Guide.

11.19 PICDEM 17 Demonstration Board

The PICDEM 17 demonstration board is an evaluation board that demonstrates the capabilities of several Microchip microcontrollers, including PIC17C752, PIC17C756A, PIC17C762 and PIC17C766. A programmed sample is included. The PRO MATE II device programmer, or the PICSTART Plus development programmer, can be used to reprogram the device for user tailored application development. The PICDEM 17 demonstration board supports program download and execution from external on-board FLASH memory. A generous prototype area is available for user hardware expansion.

12.0 ELECTRICAL SPECIFICATIONS

Absolute Maximum Ratings †

Ambient Temperature under bias	-40° to +125°C
Storage Temperature	-65° to +150°C
Voltage on any pin with respect to VSS (except VDD and $\overline{\text{MCLR}}$)	-0.6V to VDD +0.6V
Voltage on VDD with respect to VSS	0 to +7.5V
Voltage on $\overline{\text{MCLR}}$ with respect to VSS (Note 2)	0 to +14V
Voltage on RA4 with respect to VSS	8.5V
Total power Dissipation (Note 1)	1.0W
Maximum Current out of VSS pin	300 mA
Maximum Current into VDD pin	250 mA
Input Clamp Current, I _{IK} (V _I < 0 or V _I > VDD)	±20 mA
Output Clamp Current, I _{OK} (V _O < 0 or V _O > VDD)	±20 mA
Maximum Output Current sunk by any I/O pin	25 mA
Maximum Output Current sourced by any I/O pin	25 mA
Maximum Current sunk by PORTA and PORTB	200 mA
Maximum Current sourced by PORTA and PORTB	200 mA

Note 1: Power dissipation is calculated as follows: $P_{DIS} = V_{DD} \times \{I_{DD} - \sum I_{OH}\} + \sum \{(V_{DD} - V_{OH}) \times I_{OH}\} + \sum (V_{OL} \times I_{OL})$.

2: Voltage spikes below VSS at the $\overline{\text{MCLR}}$ pin, inducing currents greater than 80 mA, may cause latchup. Thus, a series resistor of 50-100Ω should be used when applying a "low" level to the $\overline{\text{MCLR}}$ pin rather than pulling this pin directly to VSS.

† **NOTICE:** Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operation listings of this specification is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

FIGURE 12-3: PIC16C62XA VOLTAGE-FREQUENCY GRAPH, $0^{\circ}\text{C} \leq T_A \leq +70^{\circ}\text{C}$

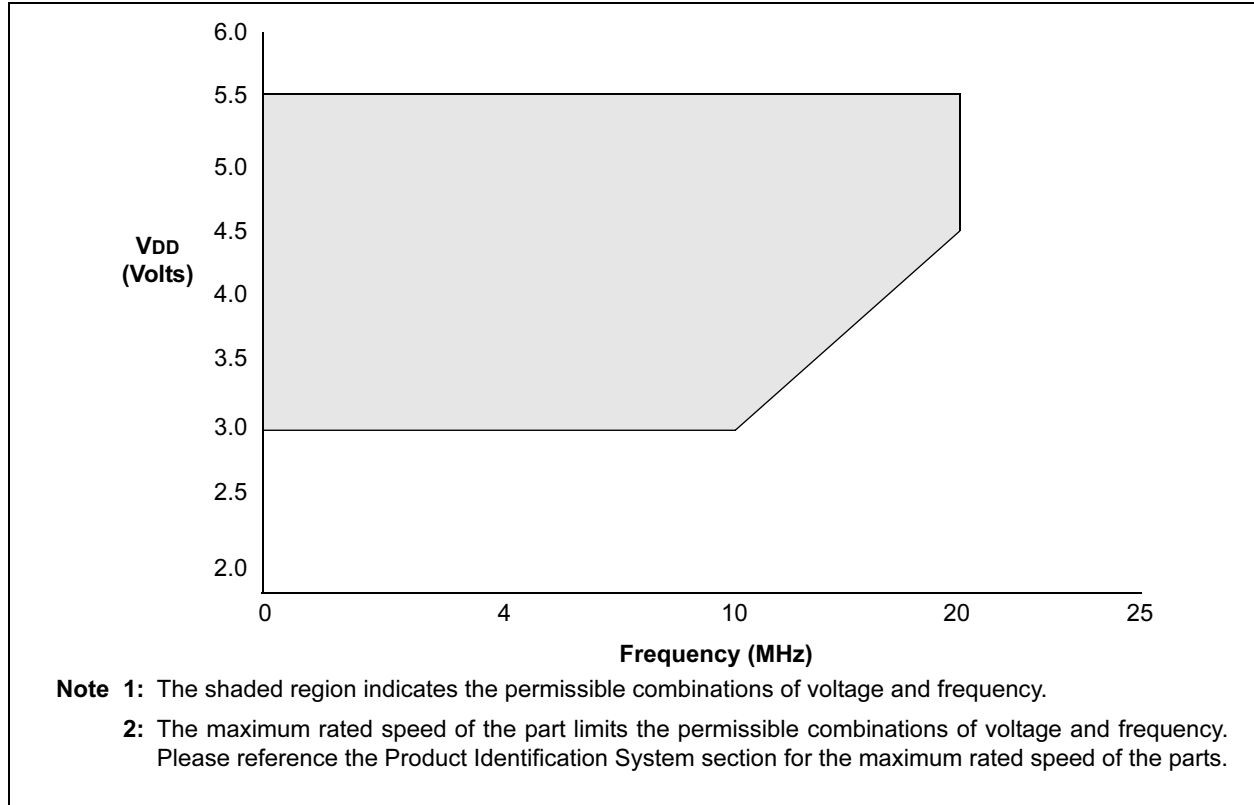
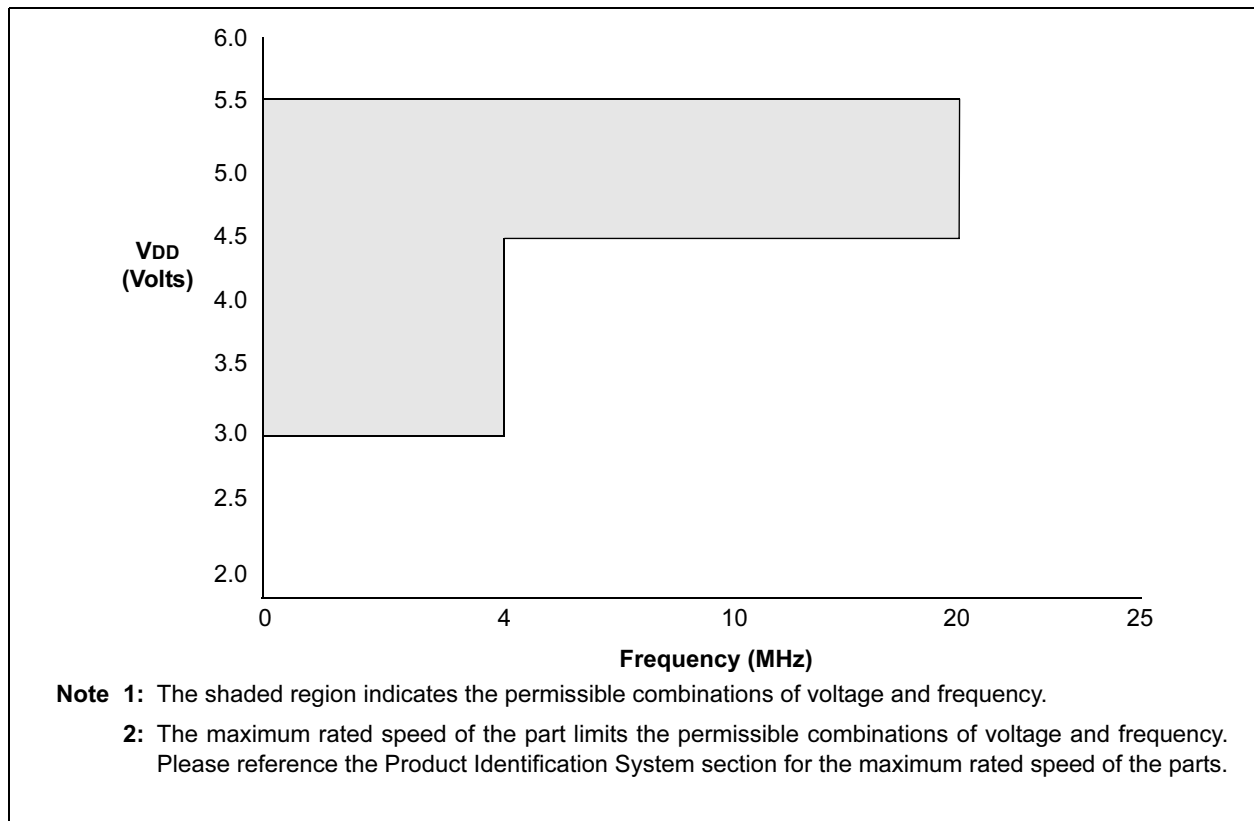


FIGURE 12-4: PIC16C62XA VOLTAGE-FREQUENCY GRAPH, $-40^{\circ}\text{C} \leq T_A \leq 0^{\circ}\text{C}$, $+70^{\circ}\text{C} \leq T_A \leq +125^{\circ}\text{C}$



12.3 DC CHARACTERISTICS: PIC16CR62XA-04 (Commercial, Industrial, Extended) PIC16CR62XA-20 (Commercial, Industrial, Extended) PIC16LCR62XA-04 (Commercial, Industrial, Extended)

PIC16CR62XA-04 PIC16CR62XA-20			Standard Operating Conditions (unless otherwise stated) Operating temperature $-40^{\circ}\text{C} \leq T_A \leq +85^{\circ}\text{C}$ for industrial and $0^{\circ}\text{C} \leq T_A \leq +70^{\circ}\text{C}$ for commercial and $-40^{\circ}\text{C} \leq T_A \leq +125^{\circ}\text{C}$ for extended				
PIC16LCR62XA-04			Standard Operating Conditions (unless otherwise stated) Operating temperature $-40^{\circ}\text{C} \leq T_A \leq +85^{\circ}\text{C}$ for industrial and $0^{\circ}\text{C} \leq T_A \leq +70^{\circ}\text{C}$ for commercial and $-40^{\circ}\text{C} \leq T_A \leq +125^{\circ}\text{C}$ for extended				
Param. No.	Sym	Characteristic	Min	Typ†	Max	Units	Conditions
D001	VDD	Supply Voltage	3.0	—	5.5	V	See Figures 12-7, 12-8, 12-9
D001	VDD	Supply Voltage	2.5	—	5.5	V	See Figures 12-7, 12-8, 12-9
D002	VDR	RAM Data Retention Voltage ⁽¹⁾	—	1.5*	—	V	Device in SLEEP mode
D002	VDR	RAM Data Retention Voltage ⁽¹⁾	—	1.5*	—	V	Device in SLEEP mode
D003	VPOR	VDD start voltage to ensure Power-on Reset	—	VSS	—	V	See section on Power-on Reset for details
D003	VPOR	VDD start voltage to ensure Power-on Reset	—	VSS	—	V	See section on Power-on Reset for details
D004	SVDD	VDD rise rate to ensure Power-on Reset	0.05*	—	—	V/ms	See section on Power-on Reset for details
D004	SVDD	VDD rise rate to ensure Power-on Reset	0.05*	—	—	V/ms	See section on Power-on Reset for details
D005	VBOR	Brown-out Detect Voltage	3.7	4.0	4.35	V	BOREN configuration bit is cleared
D005	VBOR	Brown-out Detect Voltage	3.7	4.0	4.35	V	BOREN configuration bit is cleared
D010	IDD	Supply Current ⁽²⁾	—	1.2	1.7	mA	FOSC = 4 MHz, VDD = 5.5V, WDT disabled, XT mode, (Note 4)*
			—	500	900	μA	FOSC = 4 MHz, VDD = 3.0V, WDT disabled, XT mode, (Note 4)
			—	1.0	2.0	mA	FOSC = 10 MHz, VDD = 3.0V, WDT disabled, HS mode, (Note 6)
			—	4.0	7.0	mA	FOSC = 20 MHz, VDD = 5.5V, WDT disabled*, HS mode
			—	3.0	6.0	mA	FOSC = 20 MHz, VDD = 4.5V, WDT disabled, HS mode
			—	35	70	μA	FOSC = 32 kHz, VDD = 3.0V, WDT disabled, LP mode
D010	IDD	Supply Current ⁽²⁾	—	1.2	1.7	mA	FOSC = 4.0 MHz, VDD = 5.5V, WDT disabled, XT mode, (Note 4)*
			—	400	800	μA	FOSC = 4.0 MHz, VDD = 2.5V, WDT disabled, XT mode (Note 4)
			—	35	70	μA	FOSC = 32 kHz, VDD = 2.5V, WDT disabled, LP mode

12.4 DC Characteristics: PIC16C62X/C62XA/CR62XA (Commercial, Industrial, Extended) PIC16LC62X/LC62XA/LCR62XA (Commercial, Industrial, Extended) (CONT.)

PIC16C62X/C62XA/CR62XA			Standard Operating Conditions (unless otherwise stated) Operating temperature $-40^{\circ}\text{C} \leq T_A \leq +85^{\circ}\text{C}$ for industrial and $0^{\circ}\text{C} \leq T_A \leq +70^{\circ}\text{C}$ for commercial and $-40^{\circ}\text{C} \leq T_A \leq +125^{\circ}\text{C}$ for extended				
PIC16LC62X/LC62XA/LCR62XA			Standard Operating Conditions (unless otherwise stated) Operating temperature $-40^{\circ}\text{C} \leq T_A \leq +85^{\circ}\text{C}$ for industrial and $0^{\circ}\text{C} \leq T_A \leq +70^{\circ}\text{C}$ for commercial and $-40^{\circ}\text{C} \leq T_A \leq +125^{\circ}\text{C}$ for extended				
Param. No.	Sym	Characteristic	Min	Typ†	Max	Units	Conditions
D040	V _{IH}	Input High Voltage I/O ports with TTL buffer	2.0V 0.25 V _{DD} + 0.8V	—	V _{DD} V _{DD}	V	V _{DD} = 4.5V to 5.5V otherwise (Note 1)
D041		with Schmitt Trigger input	0.8 V _{DD}	—	V _{DD}		
D042		MCLR RA4/T0CKI	0.8 V _{DD}	—	V _{DD}	V	
D043 D043A		OSC1 (XT, HS and LP) OSC1 (in RC mode)	0.7 V _{DD} 0.9 V _{DD}	—	V _{DD}	V	
D070	IPURB	PORTB weak pull-up current	50	200	400	μA	V _{DD} = 5.0V, V _{PIN} = V _{SS}
D070	IPURB	PORTB weak pull-up current	50	200	400	μA	V _{DD} = 5.0V, V _{PIN} = V _{SS}
D060	I _{IL}	Input Leakage Current ^(2, 3) I/O ports (Except PORTA)			±1.0	μA	V _{SS} ≤ V _{PIN} ≤ V _{DD} , pin at hi-impedance
D061		PORTA	—	—	±0.5	μA	V _{SS} ≤ V _{PIN} ≤ V _{DD} , pin at hi-impedance
D063		RA4/T0CKI	—	—	±1.0	μA	V _{SS} ≤ V _{PIN} ≤ V _{DD}
D063		OSC1, MCLR	—	—	±5.0	μA	V _{SS} ≤ V _{PIN} ≤ V _{DD} , XT, HS and LP osc configuration
D060	I _{IL}	Input Leakage Current ^(2, 3) I/O ports (Except PORTA)			±1.0	μA	V _{SS} ≤ V _{PIN} ≤ V _{DD} , pin at hi-impedance
D061		PORTA	—	—	±0.5	μA	V _{SS} ≤ V _{PIN} ≤ V _{DD} , pin at hi-impedance
D063		RA4/T0CKI	—	—	±1.0	μA	V _{SS} ≤ V _{PIN} ≤ V _{DD}
D063		OSC1, MCLR	—	—	±5.0	μA	V _{SS} ≤ V _{PIN} ≤ V _{DD} , XT, HS and LP osc configuration
D080	V _{OL}	Output Low Voltage I/O ports	—	—	0.6	V	I _{OL} = 8.5 mA, V _{DD} = 4.5V, -40° to $+85^{\circ}\text{C}$
			—	—	0.6	V	I _{OL} = 7.0 mA, V _{DD} = 4.5V, $+125^{\circ}\text{C}$
D083		OSC2/CLKOUT (RC only)	—	—	0.6	V	I _{OL} = 1.6 mA, V _{DD} = 4.5V, -40° to $+85^{\circ}\text{C}$
			—	—	0.6	V	I _{OL} = 1.2 mA, V _{DD} = 4.5V, $+125^{\circ}\text{C}$

* These parameters are characterized but not tested.

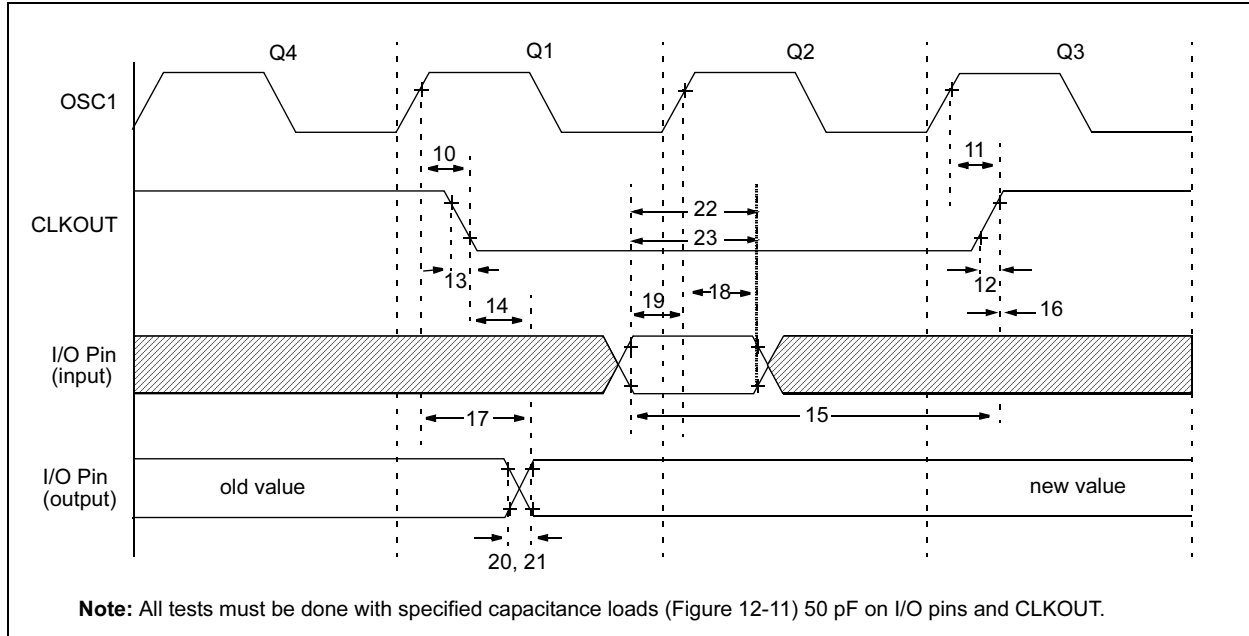
† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: In RC oscillator configuration, the OSC1 pin is a Schmitt Trigger input. It is not recommended that the PIC16C62X(A) be driven with external clock in RC mode.

2: The leakage current on the MCLR pin is strongly dependent on applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltages.

3: Negative current is defined as coming out of the pin.

FIGURE 12-13: CLKOUT AND I/O TIMING



PIC16C62X

FIGURE 12-16: TIMER0 CLOCK TIMING

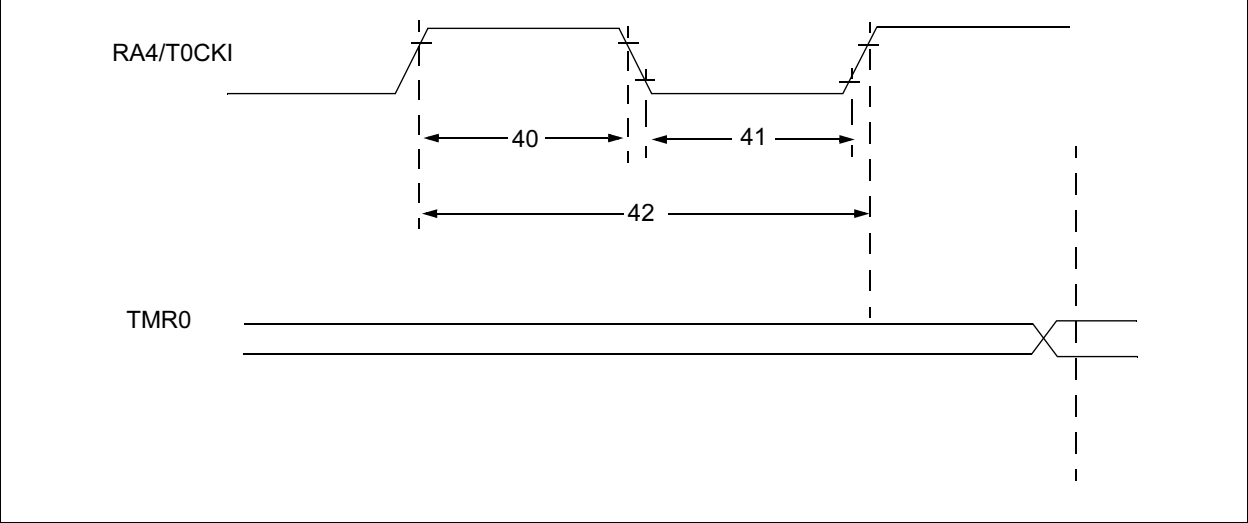


TABLE 12-6: TIMER0 CLOCK REQUIREMENTS

Parameter No.	Sym	Characteristic		Min	Typ†	Max	Units	Conditions
40	Tt0H	T0CKI High Pulse Width	No Prescaler	0.5 TcY + 20*	—	—	ns	
			With Prescaler	10*	—	—	ns	
41	Tt0L	T0CKI Low Pulse Width	No Prescaler	0.5 TcY + 20*	—	—	ns	
			With Prescaler	10*	—	—	ns	
42	Tt0P	T0CKI Period		$\frac{TcY + 40^*}{N}$	—	—	ns	N = prescale value (1, 2, 4, ..., 256)

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5.0V, 25°C, unless otherwise stated. These parameters are for design guidance only and are not tested.

PIC16C62X

FIGURE 13-3: I_{DD} VS. V_{DD} (XT OSC 4 MHZ)

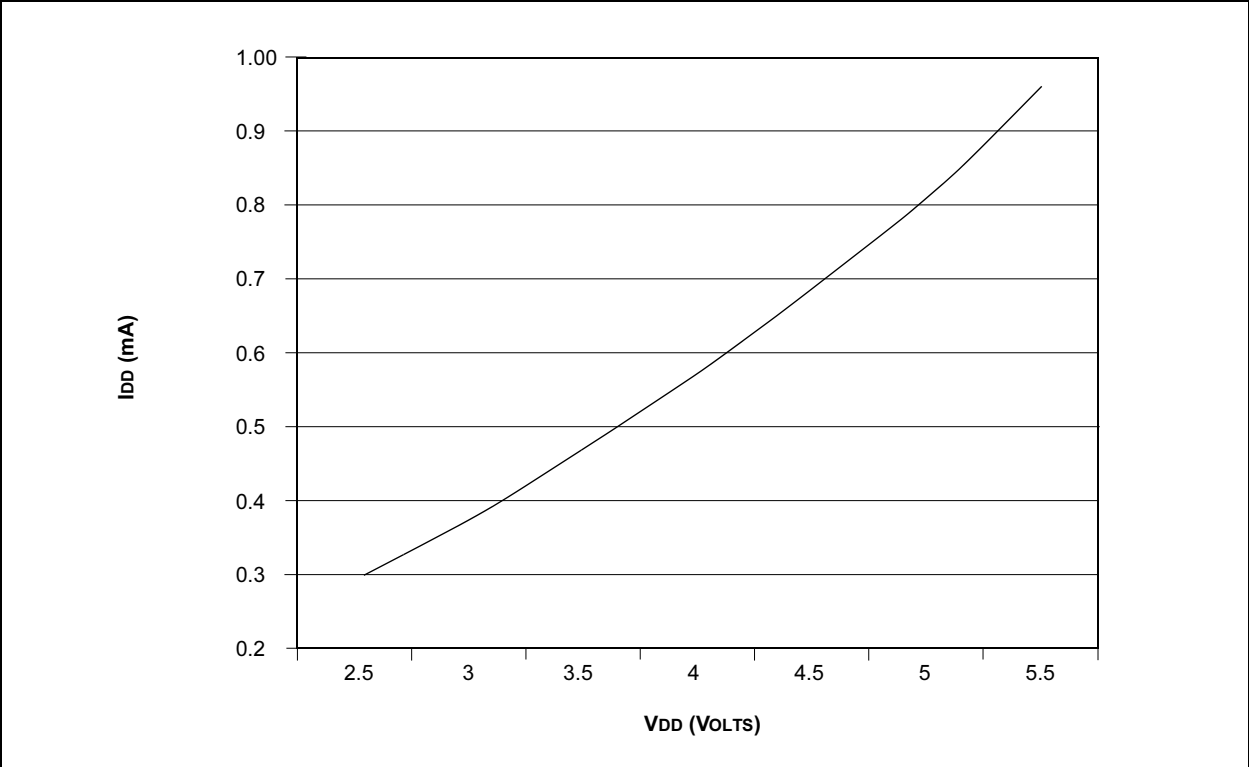
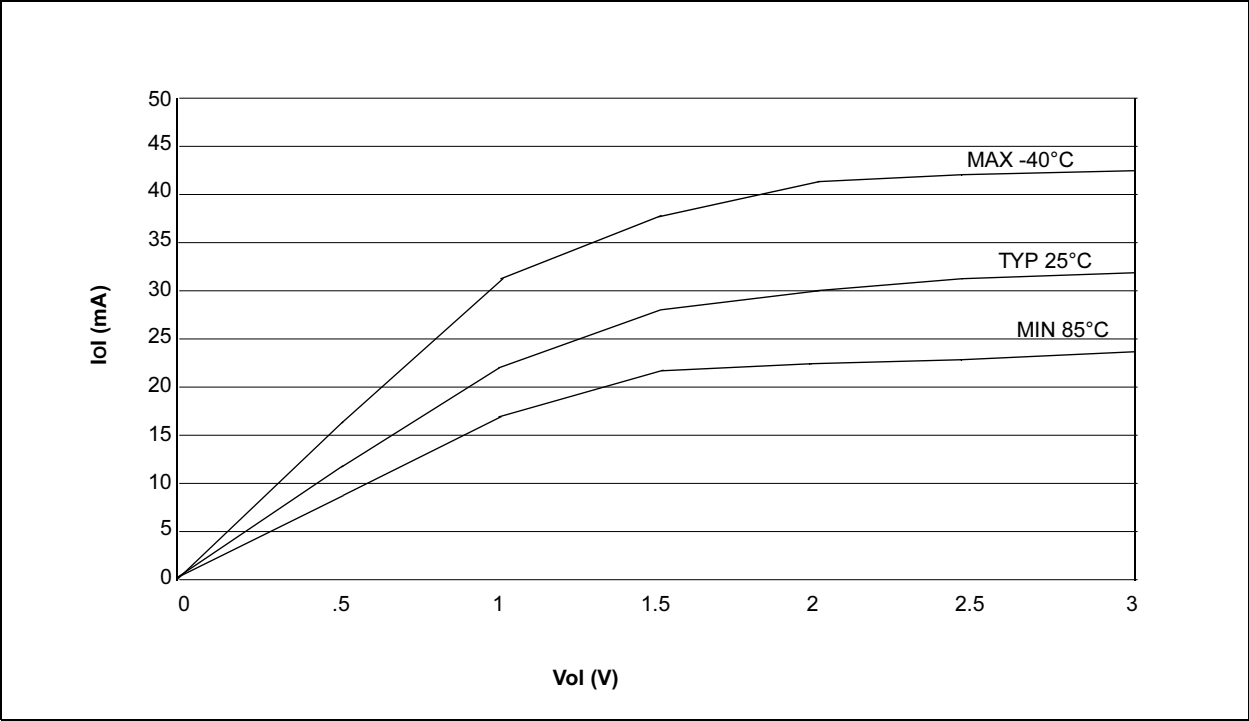
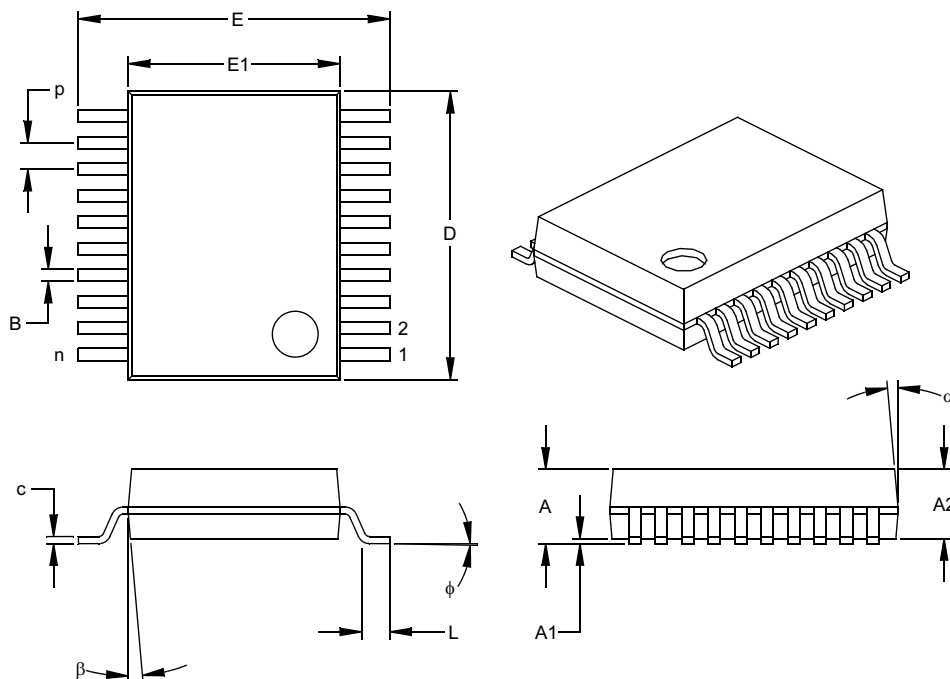


FIGURE 13-4: I_{OL} vs. V_{OL}, V_{DD} = 3.0V



PIC16C62X

20-Lead Plastic Shrink Small Outline (SS) – 209 mil, 5.30 mm (SSOP)



Units		INCHES*			MILLIMETERS		
Dimension Limits		MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins	n		20			20	
Pitch	p		.026			0.65	
Overall Height	A	.068	.073	.078	1.73	1.85	1.98
Molded Package Thickness	A2	.064	.068	.072	1.63	1.73	1.83
Standoff §	A1	.002	.006	.010	0.05	0.15	0.25
Overall Width	E	.299	.309	.322	7.59	7.85	8.18
Molded Package Width	E1	.201	.207	.212	5.11	5.25	5.38
Overall Length	D	.278	.284	.289	7.06	7.20	7.34
Foot Length	L	.022	.030	.037	0.56	0.75	0.94
Lead Thickness	c	.004	.007	.010	0.10	0.18	0.25
Foot Angle	φ	0	4	8	0.00	101.60	203.20
Lead Width	B	.010	.013	.015	0.25	0.32	0.38
Mold Draft Angle Top	α	0	5	10	0	5	10
Mold Draft Angle Bottom	β	0	5	10	0	5	10

* Controlling Parameter

§ Significant Characteristic

Notes:

Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010" (0.254mm) per side.

JEDEC Equivalent: MO-150

Drawing No. C04-072